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Kikuchi et al.(10) **Pub. No.: US 2023/0232603 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SOLDER PRINTING INSPECTION DEVICE**(71) Applicant: **CKD CORPORATION**, Aichi (JP)(72) Inventors: **Kazuyoshi Kikuchi**, Aichi (JP);
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ABSTRACT

A solder printing inspection device includes: an illumination device that irradiates, with a predetermined light, a printed circuit board on which a solder paste is printed; an imaging device that takes an image of the printed circuit board irradiated with the predetermined light and obtains image data; and a control device that: based on the image data, obtain three-dimensional measurement data of the solder paste printed on the printed circuit board, based on the three-dimensional measurement data, extracts upper portion shape data of an upper portion of the solder paste, the upper portion having a height equal to or higher than a predetermined height, and compares the upper portion shape data with a predetermined criterion and determines whether a quality of a three-dimensional shape of the upper portion of the solder paste is good or poor.

